



100% Material Declaration Data Sheet FGG900

PK114 (v1.3) September 13, 2007

Material Declaration Data Sheet

Average Weight: 4.2 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.119328	2.84%
	Silicon	7440-21-3	100.00		0.119328	
Die Attach Material					0.0105	0.25%
	Silver	7440-22-4	78.00		0.00819	
	Resin	Trade Secret	22.00		0.00231	
Mold Compound					1.73292	41.26%
	Epoxy Resins	Trade Secret	6.00		0.1039752	
	Phenolic Resins	Trade Secret	6.00		0.1039752	
	Carbon Black	1333-86-4	0.500		0.0086646	
	SiO2 Filler	60676-86-0	84.00		1.4556528	
	Bismuth	7440-69-9	Max. 1.00		0.0173292	
	Metal Hydroxide	Trade Secret	2.50		0.043323	
Laminate					1.48386	35.33%
	Bismaleimide/Triazine Board	13676-54-5/25722-66-1	17.63		0.261604518	
	Epoxy	29690-82-2	10.59		0.157140774	
	Glass Fiber (GF)	65997-17-3	15.72		0.233262792	
	Copper	7440-50-8	49.01	Metal Layer	0.727239786	
	Nickel	7440-02-0	1.32	Metal Layer	0.019586952	
	Gold	7440-57-5	0.23	Metal Layer	0.003412878	
	Brominated Resin	68541-56-0	5.50	Flame Retardant	0.0816123	
Bond Wire					0.0189	0.45%
	Gold	7440-57-5	100.00		0.0189	
Solder Balls					0.83454	19.87%
	Tin	7440-31-5	95.50		0.7969857	
	Silver	7440-22-4	4.00		0.0333816	
	Copper	7440-50-8	0.50		0.0041727	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
03/27/06	1.0	Initial release.
06/01/06	1.1	100% Material Declaration.
09/22/06	1.2	Updated component descriptions.
09/13/07	1.3	Updated component descriptions and weights